V_{CC}

] 20UT

6 COMREF

2LINE

5

D PACKAGE

(TOP VIEW)

10UT

1LINE [] 3

GND [

COMSTRB [2

- Single 5-V Supply
- ±100-mV Sensitivity
- For Application as:
 - Single-Ended Line Receiver
 - Gated Oscillator
 - Level Comparator
- Adjustable Reference Voltage
- TTL Outputs
- TTL-Compatible Strobe
- Designed for Party-Line (Data-Bus) Applications
- Common Reference-Voltage Pin
- Common Strobe

description/ordering information

This device consists of a dual single-ended line receiver with TTL-compatible strobes and outputs. The reference voltage (switching threshold) is applied externally and can be adjusted from 1.5 V to 3.4 V, making it possible to optimize noise immunity for a given system design. Due to the low input current (less than 100 μ A), the device is suited ideally for party-line (data-bus) systems.

The SN74LS2323 has a common reference-voltage pin and a common strobe.

ORDERING INFORMATION

| TA | PACI | KAGEŤ | ORDERABLE PART NUMBER | TOP-SIDE MARKING |
|-------------|----------|---------------|-----------------------|---------------------|
| 200 1 7000 | 0010 B | Tube | SN74LS2323D | 1.00000 |
| 0°C to 70°C | SOIC - D | Tape and reel | SN74LS2323DR | LS2323 |

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE (each receiver)

| LINE INPUT | STROBE | OUTPUT |
|------------------------------|--------|--------|
| ≤(V _{REF} - 100 mV) | L | Н |
| ≥(V _{REF} + 100 mV) | Х | L |
| X | Н | L |

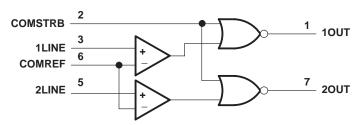
H = high level, L = low level, X = irrelevant



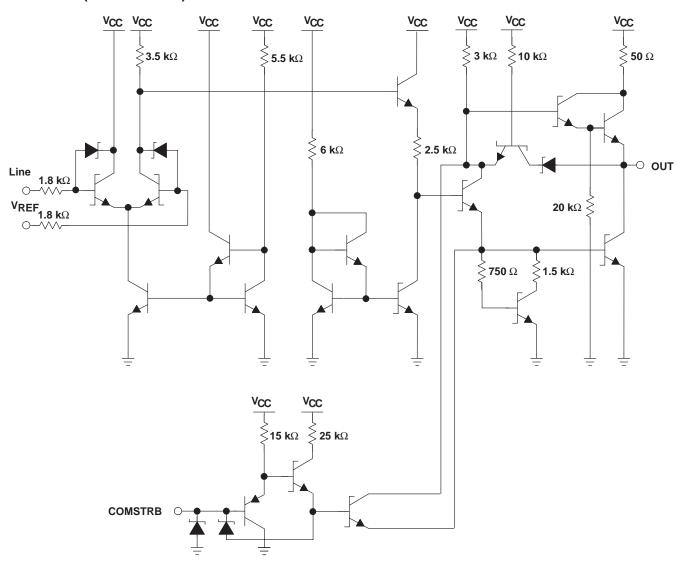
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logic diagram (positive logic)



schematic (each receiver)





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

| Supply voltage, V _{CC} (see Note 1) | $\dots \dots $ |
|--|--|
| Reference input voltage, V _{REF} | 5.5 V |
| Line input voltage range with respect to GND | –2 V to 7 V |
| Line input voltage with respect to V _{REF} | $\dots \dots \pm 5 \ V$ |
| Strobe input voltage, V _{I(S)} | $\dots \dots $ |
| Strobe input voltage, $V_{I(S)}$ | 97°C/W |
| Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds | 260°C |
| Storage temperature range, T _{stq} | 65°C to 150°C |

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

| | | MIN | NOM | MAX | UNIT |
|-------------------|--------------------------------------|-----|-----|---------------------|------|
| VCC | Supply voltage | 4.5 | 5 | 5.5 | V |
| V _{ref} | Reference input voltage | 1.8 | | ‡ | V |
| V _{I(L)} | High-level line input voltage | 0 | | V _{CC} – 1 | V |
| V _{I(S)} | High-level strobe input voltage | 0 | | 7 | V |
| TA | Operating free-air temperature range | 0 | | 70 | °C |

 $[\]frac{1}{1}$ Max = V_{CC}-1.5 V > V_{REF} < 3.4 V



NOTES: 1. Unless otherwise specified, voltage values are with respect to network ground terminal.

^{2.} The package thermal impedance is calculated in accordance with JESD 51-7.

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electrical characteristics over recommended operating free-air temperature range, V_{CC} = 5 V $\pm 10\%,\,V_{REF}$ = 1.5 V to 3.5 V (unless otherwise noted)

| | PARAMETER | TEST CONDITIONS | | MIN | MAX | UNIT |
|-----------------------|---|---|---|------|------|----------|
| Marin | High level line input value | $V_{I(S)}$ = 0.8 V, I_{OL} = 12 mA, V_{REF} = 2.5 V, $V_{OL} \le$ 0.6 V | V _{CC} = 4.5 V | 2.62 | 6 | ٧ |
| V _{IH(L)} | High-level line input voltage | $\begin{aligned} & V_{I(S)} = 0.8 \text{ V}, \text{ I}_{OL} = 16 \text{ mA}, \text{ V}_{REF} = 3.4 \text{ V}, \\ & V_{OL} \leq 0.5 \text{ V} \end{aligned}$ | V _{CC} = 5.5 V | 3.5 | 7 | V |
| ,, | | $V_{I(S)} = 0.8 \text{ V}, I_{OH} = -0.4 \text{ mA}, V_{REF} = 2.5 \text{ V}, V_{OH} \ge 2 \text{ V}$ | V _{CC} = 4.5 V | -2 | 2.38 | ,, |
| V _{IL(L)} | Low-level line input voltage | $V_{I(S)} = 0.8 \text{ V}, I_{OH} = -0.4 \text{ mA}, V_{REF} = 3.4 \text{ V}, V_{OH} \ge 3.2 \text{ V}$ | V _{CC} = 5.5 V | -2 | 3.3 | V |
| V _{IH} (S) | High-level output control input voltage | $V_{I(L)} = 1.8 \text{ V}, V_{REF} = 2.5 \text{ V}, V_{O} \le 0.4 \text{ V}$ | V _{CC} = 4.5 V | 2 | | V |
| V _{IL} (S) | Low-level output control input voltage | $V_{I(L)} = 1.8 \text{ V}, V_{REF} = 2.5 \text{ V}, V_{O} \ge 2.4 \text{ V}$ | V _{CC} = 4.5 V | | 0.8 | V |
| | | | V _{CC} = 4.5 V | 2 | | |
| Vон | High-level output voltage | $V_{I(L)} = 1.4 \text{ V}, V_{I(S)} = 0.8 \text{ V}, I_{OH} = -1 \text{ mA},$ $V_{RFF} = 2.5 \text{ V}$ | V _C C = 5 V | 2.7 | | V |
| | | VKEF - 2.0 V | $V_{CC} = 5.5 \text{ V}$ | 2.7 | | |
| | | | $V_{CC} = 4.5 \text{ V},$ $I_{OL} = 16 \text{ mA}$ | | 0.6 | |
| VOL | Low-level output voltage | $V_{I(L)} = 3.8 \text{ V}, V_{I(S)} = 0.8 \text{ V}, V_{REF} = 2.5 \text{ V}$ | V _{CC} = 5 V, I _{OL} = 24 mA | | 0.5 | V |
| | | | V _{CC} = 5.5 V, I _{OL} = 24 mA | | 0.5 | |
| | High-level input current | V 00VV 05V | $V_{CC} = 5.5 \text{ V},$ $V_{I(S)} = 2.4 \text{ V}$ | | 20 | |
| IIH(S) | | $V_{I(L)} = 3.8 \text{ V}, V_{REF} = 2.5 \text{ V}$ | $V_{CC} = 5.5 \text{ V},$ $V_{I(S)} = 7 \text{ V}$ | | 100 | μA 00 |
| | | V 24VV 25V | V _{CC} = 5 V, V _{I(L)} = 5 V | | 100 | μА |
| I _{IH(L)} | High-level input current | $V_{I(S)} = 2.4 \text{ V}, V_{REF} = 2.5 \text{ V}$ | V _{CC} = 5 V, V _{I(L)} = 5.5 V | | 2 | mA |
| I _{IH} (REF) | High-level input current | V _{I(S)} = 2.4 V, V _{REF} = 3.4 V | V _{CC} = 5.5 V, V _{I(L)} = 2.5 V | | 500 | μА |
| I _{IL(S)} | Low-level input current | V _{I(L)} = 1.8 V, V _{REF} = 0.1 V | $V_{CC} = 5.5 \text{ V},$ $V_{I(S)} = 0.4 \text{ V}$ | | -400 | μА |
| I _{IL(L)} | Low-level input current at Line input | V _{I(L)} = 0.1 V, V _{REF} = 1.8 V | $V_{CC} = 5.5 \text{ V},$ $V_{I(S)} = 0.4 \text{ V}$ | | -100 | μΑ |
| IL(REF) | Low-level input current at REF pin | V _{I(L)} = 1.8 V, V _{REF} = 0.1 V | $V_{CC} = 5.5 \text{ V},$ $V_{I(S)} = 0.4 \text{ V}$ | | -100 | μΑ |
| los | Short-circuit output current [‡] | V _{I(L)} = 1.8 V, V _{REF} = 2.8 V | V _{CC} = 5.5 V V _I (S) = 0.4 V | -30 | -130 | mA |
| ІССН | Supply current, output high | $V_{I(S)} = 0,$ $V_{CC} = 5.5 \text{ V}$ $V_{I(L)} = V_{REF} -$ | 100 mV | | 12 | mA |
| ICCL | Supply current, output low | $V_{I(S)} = 0,$ $V_{CC} = 5.5 V$ $V_{I(L)} = V_{REF} +$ | 100 mV | | 16 | mA |

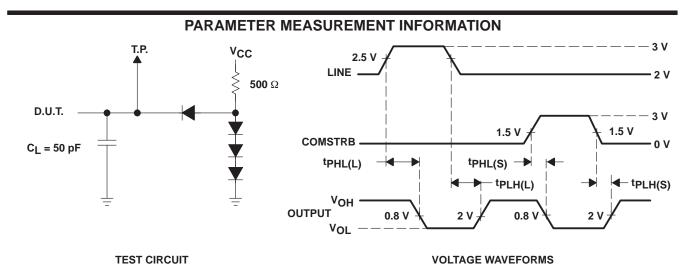
[†] Only one output should be shorted at a time, and duration of the short circuit should not exceed one second.



switching characteristics, V_{CC} = 5 V $\pm 10\%$, V_{REF} = 2.5 V, T_A = 0°C to 70°C

| | PARAMETER | TEST CONDITIONS | MIN | TYP [†] | MAX | UNIT |
|---------|---|---|-----|------------------|-----|------|
| tPLH(L) | Propagation delay time, low- to high-level output from LINE | C_L = 50 pF, R_L = 500 Ω , See Figure 1 | 10 | 25 | 35 | ns |
| tPHL(L) | Propagation delay time, high- to low-level output from LINE | C_L = 50 pF, R_L = 500 Ω , See Figure 1 | 10 | 25 | 35 | ns |
| tPLH(S) | Propagation delay time, low- to high-level output from COMSTRB | C_L = 50 pF, R_L = 500 Ω , See Figure 1 | | 11 | 22 | ns |
| tPHL(S) | Propagation delay time, high- to low-level output from COMSTRB | C_L = 50 pF, R_L = 500 Ω , See Figure 1 | | 8 | 15 | ns |

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.



NOTES: A. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, t_Γ and $t_f \leq$ 2 ns, and duty cycle = 50%.

- B. C_L includes probe and jig capacitance.
- C. All diodes are 1N914 (or equivalent).
- D. The outputs are measured one at a time, with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



TAPE AND REEL INFORMATION





| A0 | Dimension designed to accommodate the component width |
|----|---|
| В0 | Dimension designed to accommodate the component length |
| K0 | Dimension designed to accommodate the component thickness |
| W | Overall width of the carrier tape |
| P1 | Pitch between successive cavity centers |

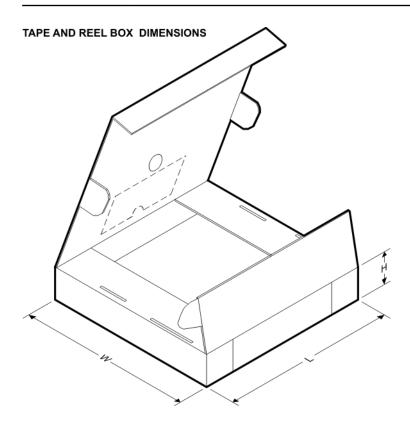
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

| Device | | Package Drawing | | | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|--------------|------|--------------------|---|------|--------------------------|--------------------------|---------|---------|---------|------------|-----------|------------------|
| SN74LS2323DR | SOIC | D | 8 | 2500 | 330.0 | 12.4 | 6.4 | 5.2 | 2.1 | 8.0 | 12.0 | Q1 |



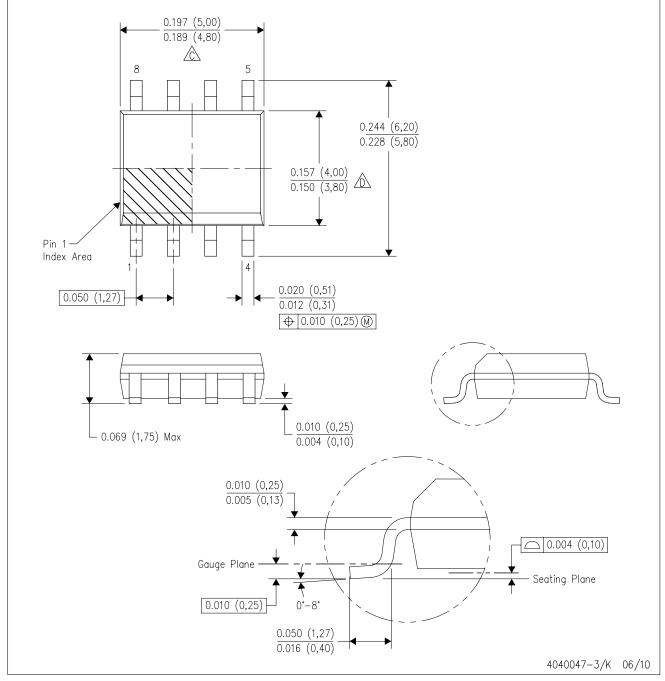


*All dimensions are nominal

| ſ | Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|---|--------------|--------------|-----------------|------|------|-------------|------------|-------------|
| I | SN74LS2323DR | SOIC | D | 8 | 2500 | 340.5 | 338.1 | 20.6 |

D (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



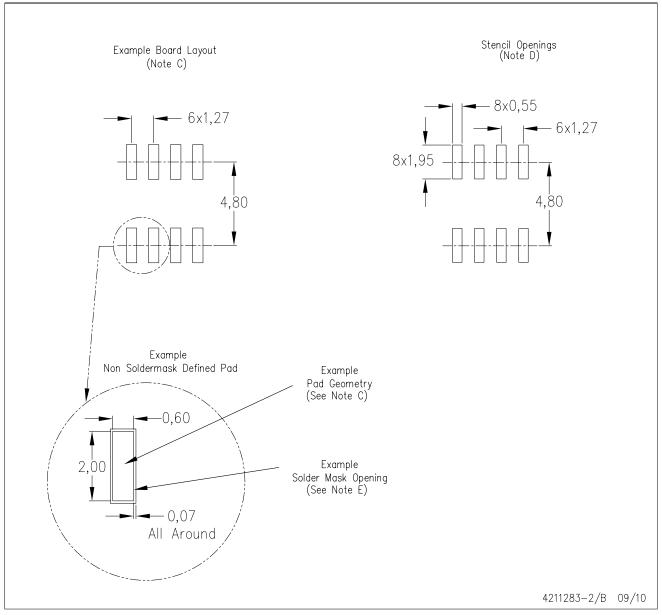
NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AA.



D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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